



## Material Content Data Sheet



<b>Sales Product Name</b>		2EDL23N06PJ		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001140332						
<b>Package</b>		PG-DSO-14-49		<b>Weight*</b>		139.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.871	1.34	1.34	13450	13450
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		103	
	non noble metal	zinc	7440-66-6	0.057	0.04		413	
	non noble metal	iron	7439-89-6	1.150	0.83		8265	
wire	non noble metal	copper	7440-50-8	46.675	33.56	34.44	335588	344369
	noble metal	gold	7440-57-5	0.258	0.19	0.19	1856	1856
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.12		1247
	plastics	epoxy resin	-	9.368	6.74		67358	
	inorganic material	silicondioxide	60676-86-0	77.202	55.51	62.37	555078	623683
leadfinish	non noble metal	tin	7440-31-5	1.226	0.88	0.88	8816	8816
plating	noble metal	silver	7440-22-4	0.307	0.22	0.22	2204	2204
glue	plastics	acrylic resin	-	0.172	0.12		1237	
	noble metal	silver	7440-22-4	0.610	0.44	0.56	4385	5622
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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